





## **MVD Strip Front-end Electronics Status**





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## **The PANDA MVD Strip Detector**

-Innermost detector of the PANDA Target Spectrometer -Located at the crossing of beam pipe and target pipe





-Tracking of charged particles -Vertex reconstruction for primary and secondary vertices

-Improvement of momentum resolution and PID







## **The PANDA MVD Strip Detector**

- Hybrid silicon pixel sensors
- Double-sided silicon strip sensors
- 4 barrel layers
  - 2 pixel barrels
  - 2 strip barrels
- 6 disk layers
  - 4 pixel disks
  - 2 mixed disks (inner pixel, outer strips)









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- 200,000 strip channels  $\rightarrow$  3112 front-ends (64 chn.) self-triggering readout!









## **Strip DAQ Chain**









## **Strip DAQ Chain**









#### **Strip Detectors**

- Barrel sensors
  - rectangular 60x35 mm<sup>2</sup> 896+512 strips

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- square 35x35 mm<sup>2</sup> 512+512 strips
- 65 µm strip pitch
  - $\rightarrow$  130 µm readout pitch

- **Disk sensors** 
  - trapezoidal 58 mm high, 37 mm long side

- 768+768 strips
- 15° stereo angle
- 45 µm strip pitch  $\rightarrow$  90 µm readout pitch

**JLU Gießen** 

**IKP** Jülich





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## PASTA

- 200,000 channels on 296 sensors need to be read out

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- PASTA PANDA Strip ASIC -
- Measurement concept inspired by TOFPET architecture
  - ASIC for SiPM readout from EndoTOFPET-US collaboration
  - self-triggering, fully digital back-end
- Complete redesign of analog stage for strip detectors
- Time-over-Threshold (ToT) using analog interpolators
  - multiple ToT stages to reduce pile-up
  - low power consumption
  - precise time resolution
- Joint development of: •
  - University Gießen
  - Forschungszentrum Jülich
  - **INFN** Torino







## PASTA

- **Requirements:** •
  - event rate up to 40 kHz per strip
  - detector capacitance 10-25 pF
  - input charge 1-40 pC (10 MIPs)
- Goals: •
  - linear time measurement with input charge

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- 8 bit dynamic range
- 50-200 ps time bin width
- noise < 1500 e<sup>-</sup>
- power consumption < 4 mW/chn</li>







## PASTA

- Architecture of the chip ullet
  - 2 discriminators for each of the 64 channels

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4 time-to-analog converters (TAC) per discriminator •



#### technical advisors: A. Rivetti, M. Rolo





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#### **PASTA Features**

- Dual threshold concept •
  - time information t<sub>1</sub> from lower threshold Vth\_T  $\rightarrow$  reduce time-walk
  - hit validation from higher threshold Vth E
  - ToT: t1 to t3

- Time measurement
  - coarse time from chip clock
  - fine time from interpolation (interpolation factor 128x @160 MHz  $\rightarrow$  50 ps bin size)









- Analog front-end
- Design carried out by Valentino Di Pietro •

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peaking time ~ 30 ns





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#### **PASTA Front-end**

- Analog front-end
  - Design comprises
    - preamplifier
    - calibration circuit
    - peaking time adjuster
    - current buffer
    - ToT amplifier
    - baseline restorer
    - hysteresis comperators
    - delay line
    - local DACs







#### **PASTA Front-end**

- Analog front-end
- Calibration pulse to front-end
  - amplitude controlled via 6 bit DAC
  - initiated by a test pulse
  - source of test pulse:
    - external signal from I/O pad
    - internal pulse generated by GCTRL
- Test pulse to TDC controller
  - initiates TDC ramping without front-end

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test readout independent of front-end input







- Linearity from simulations ullet
  - good linearity at low input charges
  - deviations compensated by calibration

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- Linearity from simulations •
  - good linearity at low input charges
  - deviations compensated by calibration

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R. Schnell, PANDA DAQT-FEE Workshop, GSI - April 9/10, 2015







- Noise (ENC) from simulations •
  - p-side: 500 e<sup>-</sup> @ 20 pF
  - case of application: 350 e- @ 10 pF

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- Noise (ENC) from simulations •
  - n-side: 600 e<sup>-</sup> @ 20 pF
  - case of application: 550 e- @ 17 pF

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### **PASTA TDC**

- Time-to-Digital-Converter
- Design carried out by Alberto Riccardi •

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#### **PASTA TDC**

#### - TDC Implementation







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#### **PASTA TDC**

#### - TDC Implementation







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#### **PASTA TDC**

#### - TDC Implementation







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#### **PASTA TDC**

- TDC Implementation









## **PASTA Digital Control**

- **TDC Control and Global Control** \_
- Design carried out by André Goerres •

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## **PASTA Digital Control**

- TDC Control and Global Control
  - Design carried out by André Goerres
  - Rewritten TDC Control code with major simplification •
    - area reduction:  $0.11 \,\mu\text{m}^2$  to  $0.01 \,\mu\text{m}^2$

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- power reduction: 1.57 mW/chn to 0.25 mW/chn
- Integration of SEU mitigation techniques
  - protect all state machines and device registers
  - Hamming encoding
  - triple-modular redundancy







## **PASTA Digital Control**

- TDC Control and Global Control
- New features/components included
  - (optinal) skip validation
  - (de-)select use of delay line
  - synchronization chain to prevent event losses

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- asynchronous FIFO for TX data
- refresh control per TAC
- internal clock divider







## **PASTA Bugfixing (1)**

- Example on TDC Post-Layout Simulations

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## **PASTA Bugfixing (1)**

- Example on TDC Post-Layout Simulations









## **PASTA Bugfixing (1)**

- Example on TDC Post-Layout Simulations

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# **PASTA Bugfixing (2)**

- Example on Front-end Post-Integration Simulations

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16 Channels + Bias







## **PASTA Bugfixing (2)**

- Example on Front-end Post-Integration Simulations









## **PASTA Bugfixing (2)**

- Example on Front-end Post-Integration Simulations

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64 Channels + Bias









## **PASTA Chip**

analog front-end

analog TDC

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#### Layout screen-shots

digital **TDC controller** 



complete channel

200 µm gap with Pminus shell to increase resistance of substrate







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## **PASTA Chip**



4.54 mm (4.09 mm)

64 channels (without global control)

Layout screen-shots







#### **PASTA Chip** panda global controller complete ASIC 4.72 mm(4.25 *mm*) **TDC** controller 5.00 mm (4.50 mm) to scale 🛰 0.84 mm (0.76 mm) 3.78 mm (3.40 mm) André Goerres | HK50.2 Instrumentation 11 R. Schnell, PANDA DAQT-FEE Workshop, GSI - April 9/10, 2015

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#### **PASTA Status**

Power consumption based on simulations •

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| front-end | TDC   | TDC ctrl | global ctrl | drivers | total |
|-----------|-------|----------|-------------|---------|-------|
| 1.0       | 0.4   | 0.25     | 60.0        | 4 x 8.5 | 3.12  |
| mW/ch     | mW/ch | mW/ch    | mW          | mW      | mW/ch |

- target value: < 4.0 mW/ch
- (LVDS drivers instead of SLVS) •







## **PASTA Outlook**

- Analog and digital designs combined •
- Implement last modifications
- Complete fixing of issues detected from simulations
- Perform last post-integration simulations to verify design •
- Submit the chip to the foundry in April 2015 • (3-4 months to get the first prototype)

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Prepare test system for PASTA prototype tests







## **Strip DAQ Chain**









#### **Module Data Concentrator (MDC)**

- Data Concentrator ASIC at the stave level

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- Multiplexes all front-ends of one sensor
  - up to 12 front-ends per MDC
  - needs galvanic isolation of data lines, DC-balanced code
- Slow control interface to front-end chips
- Data concentration and feature extraction







#### Module Data Concentrator (MDC)









#### **Module Data Concentrator (MDC)**

Power estimation

| basic design | 68 mW  |  |  |
|--------------|--------|--|--|
| full design  | 200 mW |  |  |
| SLVS-I/Os    | 93 mW  |  |  |
| Total basic  | 161 mW |  |  |
| Total full   | 293 mW |  |  |

- Chip size estimation
  - 5.0 MGates  $\rightarrow$  approx. 22 mm<sup>2</sup> @ 230 kgates/mm<sup>2</sup>
  - 118 pads
- Use same commercial 110nm technology as PASTA
  - triple modular redundancy for all critical components







### **Module Data Concentrator (MDC)**

- Status as of March 2015
  - designed versions with/without feature extraction

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- design and simulation of FPGA prototype (VHDL-based) is finished for:
  - 12:1 Multiplexer
  - FIFO
  - front-end interface
  - 10b/8b-decoding
  - triple redundancy
- under simulation: triple redundancy
- under design/simulation: clustering/hitfinder
- to be done:
  - status and control
  - e-link
  - slow control







## **Strip DAQ Chain**







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#### **Thank you for your Attention**









### **GBT**

- Additional data concentration level
- Multiplexes several MDCs connected via e-link protocol
- Placed close to MVD •
  - reduce length of electrical links
- Fast optical links towards off-detector electronic

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3.2 Gbps user data rate









## **MVD Multiplexer Board (MMB)**

- Off-detector electronics of the MVD
- (Developed in the Helmholtz Association of German Research Centers)
- MTCA.4 compatible AMC module
  - based on Xilinx Kintex-7 FPGA
  - 4 SFP/SFP+ cages (GTX transceiver)

H. Kleines, M. Drochner, P. Wüstner ZEA-2, FZ Jülich

- Connection to PANDA time distribution system (SODANET)
- Sends data to global PANDA DAQ system (Compute Nodes)

